In the LED packaging world, Flip Chip technology is rising…
4th International LED professional Symposium +Expo (LpS 2014)
From Sept. 30 to Oct. 2nd in Bregenz, Austria

Lyon, France – September 19, 2014: In the LED packaging world, a wind of change is blowing. A LED TV crisis, and new Chinese players have totally modified the LED industry and its supply chain. Under this context, with a high competitive environment, new challenges have been identified by Yole Développement (Yole) analysts: efficacy improvement, cost decrease ... To answer to the LED market needs, companies have today to innovate their technologies and implement new solutions like Flip Chip for LED packaging.

“In 2013, LED based on Flip Chip technology represented 11% (in volume) of the overall high power LED market; such market share should reach 24% (in volume as well) by 2020”, explains Pars Mukish, Senior Market and Technology Analyst, LED, OLED & Compound Semiconductors, at Yole (Source: LED Packaging 2014 report, to be released end of September 2014).

End of September, the 4th International LED professional Symposium +Expo (LpS 2014) will take place for the second time. Located in Bregenz, Austria and targeting industrials and researchers involved in LED design and engineering, the symposium is a three-day event including conferences, workshops, networking and exhibition.

At LpS 2014, Yole will present its latest analysis, with a special focus on LED chip manufacturing and packaging. During his presentation, Pars Mukish from Yole, will highlight the recent developments dedicated to LED chip manufacturing and packaging. Yole’s analyst
will detail main market trends, emerging technologies and technical challenges including packaging process steps and supply chain ...

All these results are part of two technology & market reports, **LED Front-End Manufacturing Trends** (released in May 2014) and LED Packaging that will be released end of September 2014. “At Yole, we are daily working with the key players of the LED industry, to understand and analyze recent developments on manufacturing process and packaging solutions. Our objective is to evaluate the impact of the LED penetration rate in the solid state lighting market”, explains Pars Mukish.

LpS 2014 is a 60-lecture program and welcomes 1,300 visitors. Yole Développement invites you to meet its expert, Pars Mukish at the LpS exhibition (more than 100 booths), booth #D12.

Discover LpS 2014 agenda and registration information: [here](#).

**About Yole Développement’s reports**

- **LED Packaging**
  Resume: This report presents all materials and equipment used in LED packaging. Under this analysis, Yole Développement details the LED packaging process flow (per process steps) and analyzes key recent technological trends. All along the survey, analysts highlight the importance of cost reduction and new material/techniques development in this domain. They present related key players and the structure of the supply chain. They also provides market metrics both at LED and material/equipment levels.
  
  Publication date: September 2014
  

  More information on [www.i-micronews.com](http://www.i-micronews.com), LED reports section.

- **LED Front-End Manufacturing Trends**
  Resume: Under this report, Yole’s analyst provide a better understanding of the current process flow, process steps and technological trends in LED front-end manufacturing. Pars Mukish details the importance of cost reduction in this area as well. Moreover, he evaluates emerging substrates and related technologies including GaN-on-GaN LEDs and GaN-on-Si LEDs...

  Publication date: May 2014
  

**About Yole Développement – www.yole.fr**

Founded in 1998, Yole Développement has grown to become a group of companies providing marketing, technology and strategy consulting, media in addition to corporate finance services. With a strong focus on emerging applications using silicon and/or micro manufacturing, Yole
Développement group has expanded to include more than 50 collaborators worldwide covering MEMS, Compound Semiconductors, LED, Image Sensors, Optoelectronics, Microfluidics & Medical, Photovoltaics, Advanced Packaging, Manufacturing, Nanomaterials and Power Electronics. The group supports industrial companies, investors and R&D organizations worldwide to help them understand markets and follow technology trends to develop their business.

**Consulting activities**
- Market data & research, marketing analysis
- Technology analysis
- Reverse engineering & costing services
- Strategy consulting
- Patent analysis

More information on www.yole.fr

**Media & Events**
- i-Micronews.com, online disruptive technologies website
- @Micronews, weekly e-newsletter
- Technology Magazines dedicated to MEMS, Advanced Packaging, LED and Power Electronics
- Communication & webcasts services
- Events: Yole Seminars, Market Briefings

**Reports**
- Collection of technology & market reports
- Manufacturing cost simulation tools
- Component reverse engineering & costing analysis
- Patent investigation

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**Financial services**
- Mergers & Acquisitions
- Due diligence
- Fundraising
- Coaching of emerging companies
- IP portfolio management & optimization

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